

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

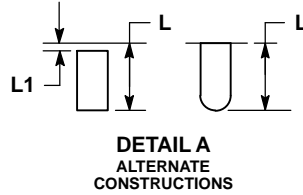
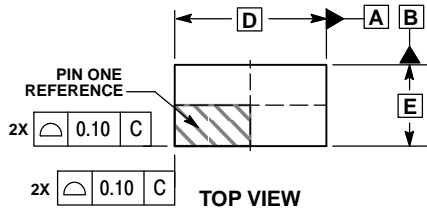
ON Semiconductor®



SCALE 4:1

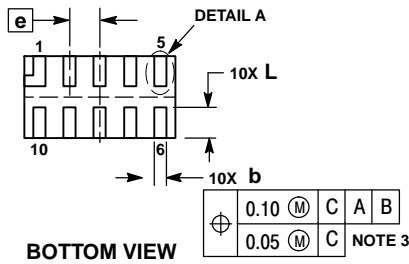
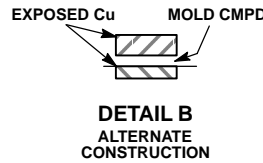
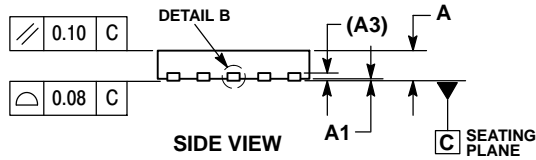
XDFN10 2.50x1.35, 0.5P
CASE 711AX
ISSUE A

DATE 12 APR 2016

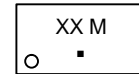


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.

DIM	MILLIMETERS	
	MIN	MAX
A	0.40	0.50
A1	0.00	0.05
A3	0.15 REF	
b	0.15	0.25
D	2.50 BSC	
E	1.35 BSC	
e	0.50 BSC	
L	0.40	0.60
L1	---	0.15



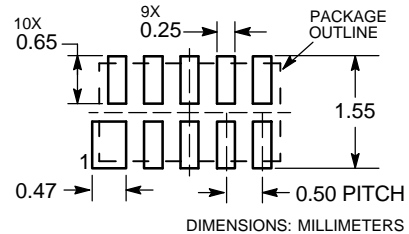
GENERIC MARKING DIAGRAM*



- XX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED MOUNTING FOOTPRINT



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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	XDFN10 2.50X1.35, 0.5P	PAGE 1 OF 2

